

Description

The HSBA100P04 is the high cell density trenched P-ch MOSFETs, which provide excellent R_{DS(ON)} and gate charge for most of the synchronous buck converter applications.

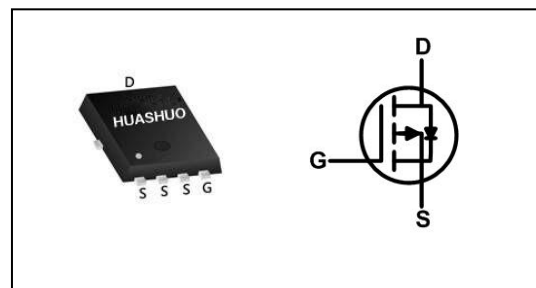
The HSBA100P04 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- Super Low Gate Charge
- 100% EAS Guaranteed
- Excellent CdV/dt effect decline
- Green Device Available
- Advanced high cell density Trench technology

Product Summary

| | | |
|-------------------------|------|----|
| V _{DS} | -40 | V |
| R _{DS(ON),max} | 5.8 | mΩ |
| I _D | -100 | A |

PRPAK5*6 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|------------------------------------|---|------------|-------|
| V _{DS} | Drain-Source Voltage | -40 | V |
| V _{GS} | Gate-Source Voltage | ± 20 | V |
| I _{D@T_C=25°C} | Continuous Drain Current, V _{GS} @ -10V ¹ | -100 | A |
| I _{D@T_C=100°C} | Continuous Drain Current, V _{GS} @ -10V ¹ | -64 | A |
| I _{DM} | Pulsed Drain Current ² | -295 | A |
| EAS | Single Pulse Avalanche Energy ³ | 380 | mJ |
| I _{AS} | Avalanche Current | -50 | A |
| P _{D@T_C=25°C} | Total Power Dissipation ⁴ | 52.1 | W |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction-Ambient ¹ | --- | 25 | °C/W |
| R _{θJC} | Thermal Resistance Junction-Case ¹ | --- | 1.8 | °C/W |

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|--|---|------|--------|-------|-------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =-250uA | -40 | --- | --- | V |
| ΔBV _{DSS} /ΔT _J | BV _{DSS} Temperature Coefficient | Reference to 25°C, I _D =-1mA | --- | -0.023 | --- | V/°C |
| R _{DS(ON)} | Static Drain-Source On-Resistance ² | V _{GS} =-10V, I _D =-20A | --- | 4.6 | 5.8 | mΩ |
| | | V _{GS} =-4.5V, I _D =-10A | --- | 6 | 7.8 | |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =-250uA | -1.2 | -1.8 | -2.5 | V |
| ΔV _{GS(th)} | V _{GS(th)} Temperature Coefficient | | --- | 4.74 | --- | mV/°C |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =-32V, V _{GS} =0V, T _J =25°C | --- | --- | 1 | uA |
| | | V _{DS} =-32V, V _{GS} =0V, T _J =55°C | --- | --- | 5 | |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} = ± 20V, V _{DS} =0V | --- | --- | ± 100 | nA |
| g _{fs} | Forward Transconductance | V _{DS} =-15V, I _D =-18A | --- | 50 | --- | S |
| R _g | Gate Resistance | V _{DS} =0V, V _{GS} =0V, f=1MHz | --- | 2.3 | --- | Ω |
| Q _g | Total Gate Charge | V _{DS} =-20V, V _{GS} =-10V, I _D =-12A | --- | 115 | --- | nC |
| Q _{gs} | Gate-Source Charge | | --- | 14 | --- | |
| Q _{gd} | Gate-Drain Charge | | --- | 26 | --- | |
| T _{d(on)} | Turn-On Delay Time | V _{DD} =-20V, V _{GS} =-10V, R _G =3Ω, I _D =-12A | --- | 19 | --- | ns |
| T _r | Rise Time | | --- | 12 | --- | |
| T _{d(off)} | Turn-Off Delay Time | | --- | 80 | --- | |
| T _f | Fall Time | | --- | 18 | --- | |
| C _{iss} | Input Capacitance | V _{DS} =-20V, V _{GS} =0V, f=1MHz | --- | 7090 | --- | pF |
| C _{oss} | Output Capacitance | | --- | 530 | --- | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 422 | --- | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|--|--|------|------|------|------|
| I _S | Continuous Source Current ^{1,5} | V _G =V _D =0V, Force Current | --- | --- | -100 | A |
| V _{SD} | Diode Forward Voltage ² | V _{GS} =0V, I _S =-1A, T _J =25°C | --- | --- | -1.2 | V |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V_{DD}=-32V, V_{GS}=-10V, L=0.1mH, I_{AS}=-50A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

Typical Characteristics

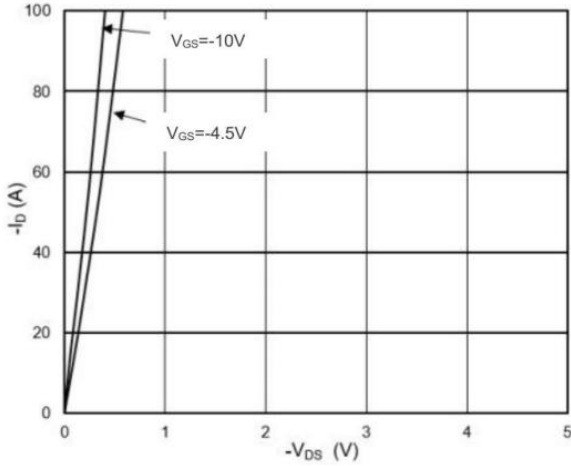


Fig.1 Typical Output Characteristics

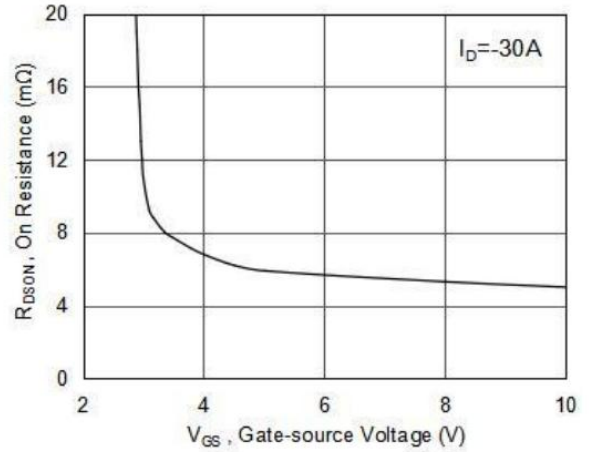


Fig.2 On-Resistance vs. G-S Voltage

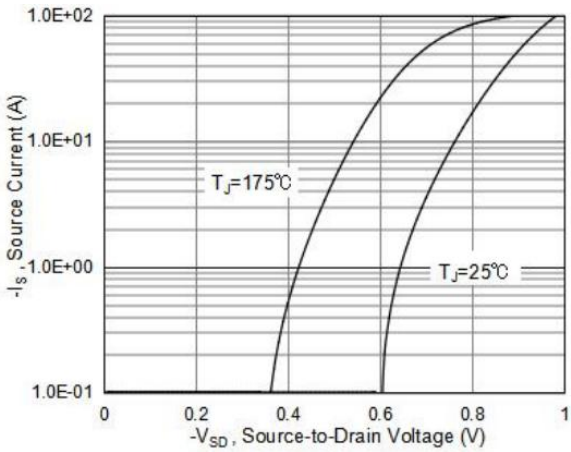


Fig.3 Typical S-D Diode Forward Voltage

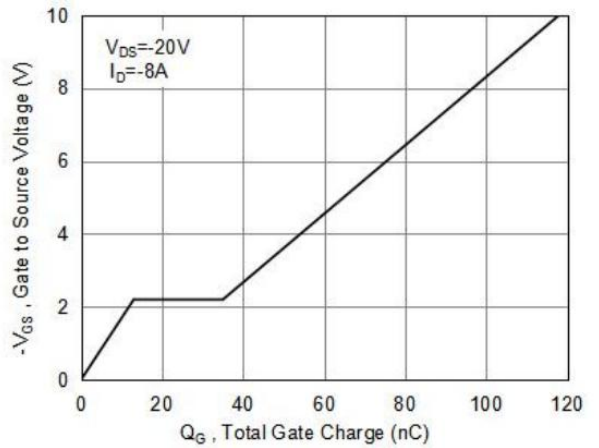


Fig.4 Gate-Charge Characteristics

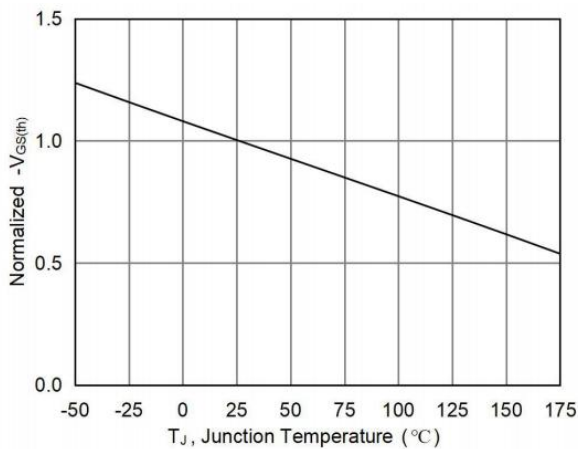


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

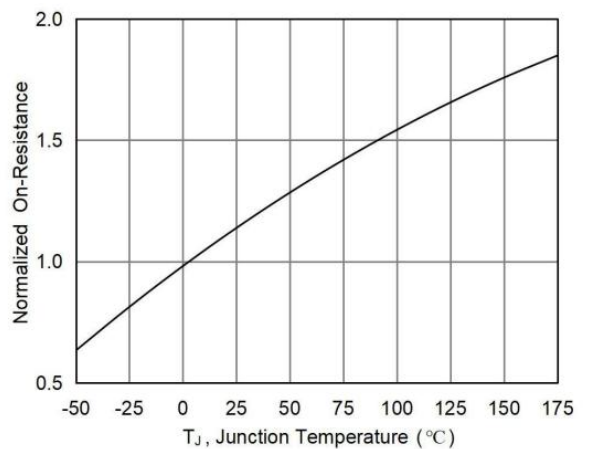


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

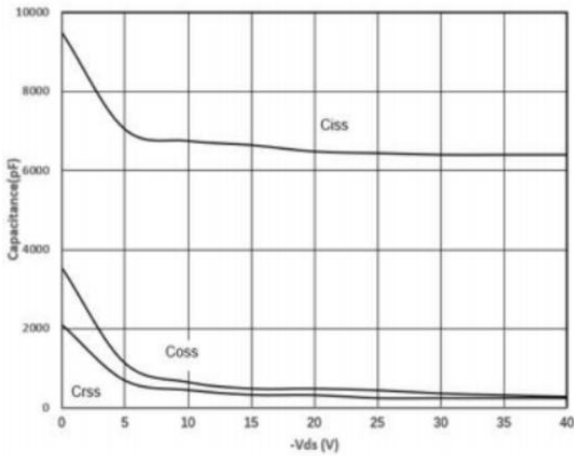


Fig.7 Capacitance

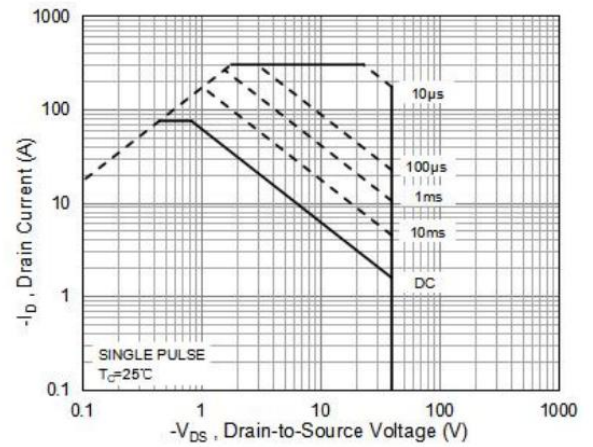


Fig.8 Safe Operating Area

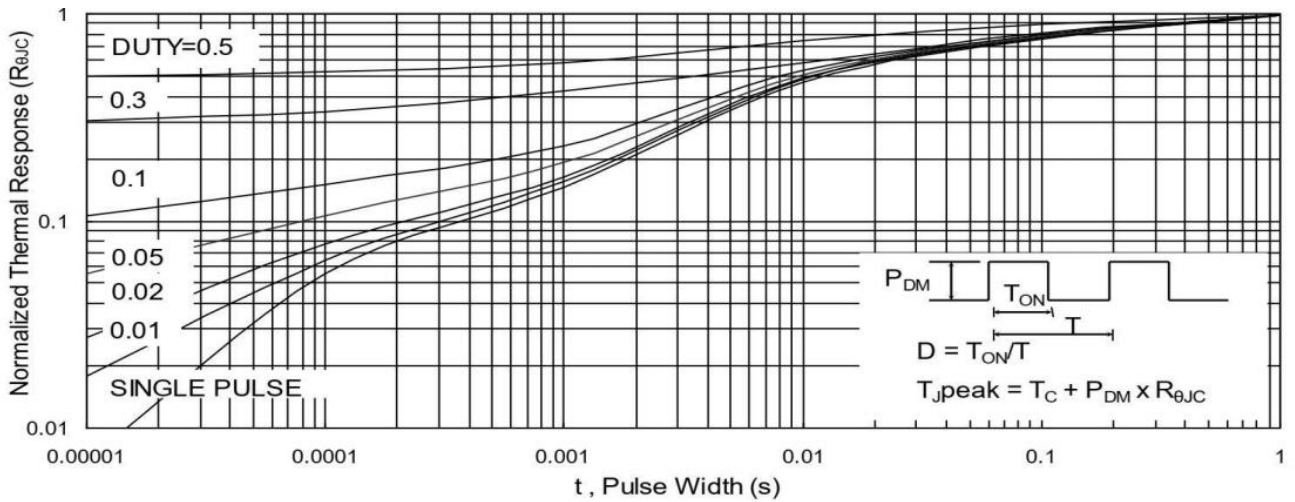


Fig.9 Normalized Maximum Transient Thermal Impedance

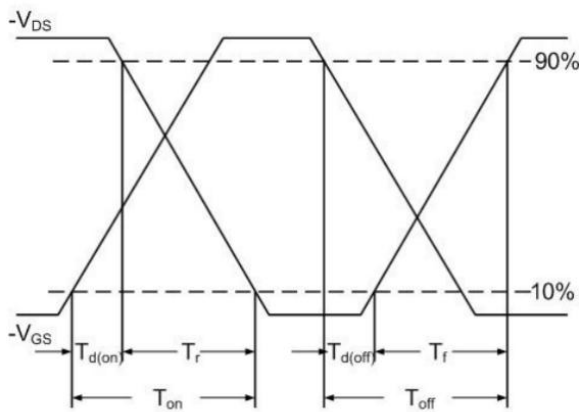


Fig.10 Switching Time Waveform

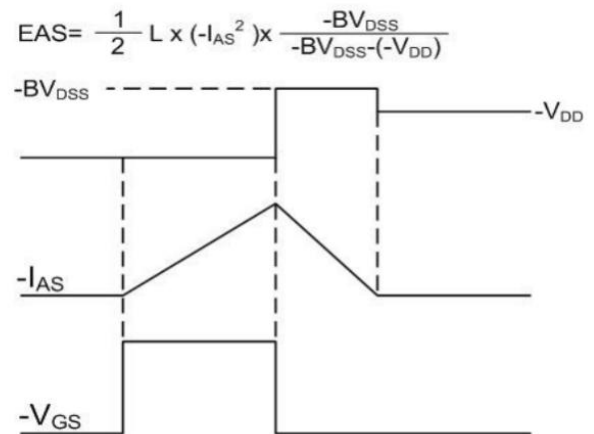
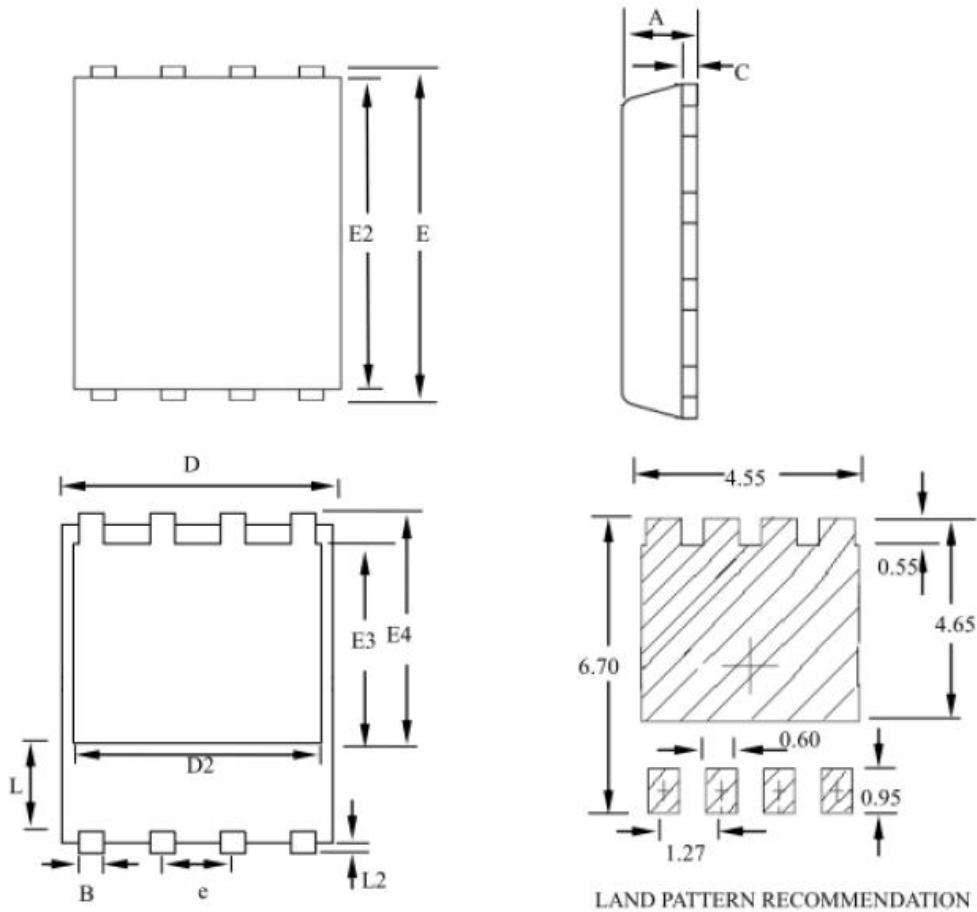


Fig.11 Unclamped Inductive Waveform

PRPAK5X6 Package Outline Dimensions



| SYMBOLS | MILLIMETERS | | | INCHES | | |
|---------|-------------|------|------|--------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.80 | -- | 1.20 | 0.031 | -- | 0.047 |
| B | 0.30 | -- | 0.51 | 0.012 | -- | 0.020 |
| C | 0.15 | -- | 0.35 | 0.006 | -- | 0.014 |
| D | 4.80 | -- | 5.30 | 0.189 | -- | 0.209 |
| D2 | 3.61 | -- | 4.35 | 0.142 | -- | 0.171 |
| E | 5.90 | -- | 6.35 | 0.232 | -- | 0.250 |
| E2 | 5.42 | -- | 5.90 | 0.213 | -- | 0.232 |
| E3 | 3.23 | -- | 3.90 | 0.127 | -- | 0.154 |
| E4 | 3.69 | -- | 4.55 | 0.145 | -- | 0.179 |
| L | 0.61 | -- | 1.80 | 0.024 | -- | 0.071 |
| L2 | 0.05 | -- | 0.36 | 0.002 | -- | 0.014 |
| e | -- | 1.27 | -- | -- | 0.050 | -- |